

In the Claims

The claims are as follows:

1 1.-10. (Canceled)

1 11. (previously presented) An apparatus for removing contaminate particulate
2 matter from a contaminate particle containing integrated circuit semiconductor
3 substrate surface comprising:

4 a support for supporting an integrated circuit semiconductor substrate
5 containing undesirable particulate matter on the surface of the substrate;

6 means for applying a sacrificial coating of a curable polymer on the surface of
7 the substrate, which curable polymer is to encapsulate and suspend the
8 undesirable particles therein;

9 means for fluidizing the curable polymer if necessary;

10 energy forming means to dislodge at least some of the particulate matter from
11 the surface of the integrated circuit semiconductor substrate into the fluid
12 curable polymer sacrificial coating such that the particulate matter is
13 partially or fully encapsulated and suspended within the sacrificial curable
14 polymer coating forming a particulate matter containing curable polymer
15 sacrificial coating;

16 means for curing the fluidized particulate matter containing curable polymer
17 sacrificial coating to form a cured polymer strippable film containing the
18 particulate matter; and
19 means for removing the particulate matter containing curable polymer
20 sacrificial strippable film from the surface of the substrate as a strippable
21 film providing a substrate surface having less particulate matter therein and
22 a stripped film containing the particles.

1 12. (Canceled)

1 13. (previously presented) The apparatus of claim 11 wherein the sacrificial
2 coating curable polymer is a fluid.

1 14. (Original) The apparatus of claim 11 wherein the energy is sonic energy.

1 15. (Original) The apparatus of claim 11 wherein the energy means is thermal,
2 centrifugal, magnetic or vibrational.

1 16. (previously presented) The apparatus of claim 11 wherein the sacrificial
2 coating curable polymer is a liquid.

1 17.-20. (Canceled)

1 21.-25. (canceled)